

Jin-Goo Park

List of Publications by Year in descending order

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186
papers

2,017
citations

279798

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all docs

186
docs citations

186
times ranked

1308
citing authors

#	ARTICLE	IF	CITATIONS
1	Interfacial and Electrokinetic Characterization of IPA Solutions Related to Semiconductor Wafer Drying and Cleaning. Journal of the Electrochemical Society, 2006, 153, G811.	2.9	85
2	Scratch formation and its mechanism in chemical mechanical planarization (CMP). Friction, 2013, 1, 279-305.	6.4	71
3	Evaluation of double sided lapping using a fixed abrasive pad for sapphire substrates. Wear, 2013, 302, 1340-1344.	3.1	66
4	Experimental and Numerical Investigation of Nanoparticle Removal Using Acoustic Streaming and the Effect of Time. Journal of the Electrochemical Society, 2006, 153, G846.	2.9	61
5	Investigation of cu-BTA complex formation during Cu chemical mechanical planarization process. Applied Surface Science, 2016, 384, 505-510.	6.1	60
6	The Effect of Additives in Post-Cu CMP Cleaning on Particle Adhesion and Removal. Journal of the Electrochemical Society, 2004, 151, G756.	2.9	59
7	On the mechanism of material removal by fixed abrasive lapping of various glass substrates. Wear, 2013, 302, 1334-1339.	3.1	55
8	Characterization of TMAH based cleaning solution for post Cu-CMP application. Microelectronic Engineering, 2013, 102, 74-80.	2.4	55
9	Effect of pH in Ru Slurry with Sodium Periodate on Ru CMP. Journal of the Electrochemical Society, 2009, 156, H188.	2.9	46
10	Effect of dissolved gases in water on acoustic cavitation and bubble growth rate in 0.83 MHz megasonic of interest to wafer cleaning. Ultrasonics Sonochemistry, 2014, 21, 1496-1503.	8.2	42
11	Characterization of non-amine-based post-copper chemical mechanical planarization cleaning solution. Microelectronic Engineering, 2014, 122, 33-39.	2.4	39
12	Selection and Optimization of Corrosion Inhibitors for Improved Cu CMP and Post-Cu CMP Cleaning. ECS Journal of Solid State Science and Technology, 2019, 8, P3058-P3062.	1.8	38
13	The Effect of Hydrogen Peroxide in a Citric Acid Based Copper Slurry on Cu Polishing. Journal of the Electrochemical Society, 2007, 154, D38.	2.9	37
14	Interaction Forces Between Silica Particles and Wafer Surfaces during Chemical Mechanical Planarization of Copper. Journal of the Electrochemical Society, 2003, 150, G327.	2.9	35
15	Comparison between sapphire lapping processes using 2-body and 3-body modes as a function of diamond abrasive size. Wear, 2015, 332-333, 794-799.	3.1	35
16	Effect of Sodium Periodate in Alumina-Based Slurry on Ru CMP for Metal-Insulator-Metal Capacitor. Electrochemical and Solid-State Letters, 2008, 11, H150.	2.2	34
17	Electrochemical Impedance Spectroscopy (EIS) Analysis of BTA Removal by TMAH during Post Cu CMP Cleaning Process. Journal of the Electrochemical Society, 2012, 159, C447-C452.	2.9	30
18	Effect of lanthanum doping in ceria abrasives on chemical mechanical polishing selectivity for shallow trench isolation. Materials Science in Semiconductor Processing, 2015, 33, 161-168.	4.0	29

#	ARTICLE	IF	CITATIONS
19	Investigation of the effect of different cleaning forces on Ce-O-Si bonding during oxide post-CMP cleaning. Applied Surface Science, 2021, 545, 149035.	6.1	29
20	Effective Carbon Contaminant Cleaning Condition Using Ozone Dissolved Water and Megasonic for Ru-Capped Extreme Ultraviolet Lithography Mask. Japanese Journal of Applied Physics, 2012, 51, 096503.	1.5	29
21	Generation of Pad Debris during Oxide CMP Process and Its Role in Scratch Formation. Journal of the Electrochemical Society, 2011, 158, H394.	2.9	28
22	Analysis of Scratches Formed on Oxide Surface during Chemical Mechanical Planarization. Journal of the Electrochemical Society, 2010, 157, H186.	2.9	26
23	A Breakthrough Method for the Effective Conditioning of PVA Brush Used for Post-CMP Process. ECS Journal of Solid State Science and Technology, 2019, 8, P307-P312.	1.8	24
24	Experimental and Analytical Study of Submicrometer Particle Removal from Deep Trenches. Journal of the Electrochemical Society, 2006, 153, C603.	2.9	23
25	A self-assembled monolayer-based micropatterned array for controlling cell adhesion and protein adsorption. Biotechnology and Bioengineering, 2011, 108, 1194-1202.	3.3	22
26	Convective Assembly and Dry Transfer of Nanoparticles Using Hydrophobic/Hydrophilic Monolayer Templates. Langmuir, 2009, 25, 11375-11382.	3.5	21
27	Laser Shock Removal of Nanoparticles from Si Capping Layer of Extreme Ultraviolet Lithography Masks. Japanese Journal of Applied Physics, 2005, 44, 5560-5564.	1.5	20
28	Enhancement of airborne shock wave by laser-induced breakdown of liquid column in laser shock cleaning. Journal of Applied Physics, 2011, 109, 073101.	2.5	20
29	Abrasive and additive interactions in high selectivity STI CMP slurries. Microelectronic Engineering, 2014, 114, 98-104.	2.4	20
30	Preparation and characterization of perfluoro-organic thin films on aluminium. Surface and Coatings Technology, 1999, 112, 48-51.	4.8	19
31	Passivation and Etching of Wafer Surfaces in HF/H ₂ O ₂ /IPA Solutions. Japanese Journal of Applied Physics, 2002, 41, 5881-5886.	1.5	19
32	Effect of processing parameters, antistiction coatings, and polymer type when injection molding microfeatures. Polymer Engineering and Science, 2010, 50, 411-419.	3.1	19
33	Influence of anionic polyelectrolyte addition on ceria dispersion behavior for quartz chemical mechanical polishing. Colloids and Surfaces A: Physicochemical and Engineering Aspects, 2012, 411, 122-128.	4.7	19
34	Tungsten passivation layer (WO ₃) formation mechanisms during chemical mechanical planarization in the presence of oxidizers. Applied Surface Science, 2021, 537, 147862.	6.1	19
35	Contamination Mechanism of Ceria Particles on the Oxide Surface after the CMP Process. ECS Journal of Solid State Science and Technology, 2020, 9, 124004.	1.8	19
36	Fabrication of a hydrophobic/hydrophilic hybrid-patterned microarray chip and its application to a cancer marker immunoassay. Biochip Journal, 2012, 6, 10-16.	4.9	18

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37	The impact of diamond conditioners on scratch formation during chemical mechanical planarization (CMP) of silicon dioxide. Tribology International, 2013, 67, 272-277.	5.9	18
38	Effect of Different Deposition Mediums on the Adhesion and Removal of Particles. Journal of the Electrochemical Society, 2010, 157, H662.	2.9	17
39	Post-CMP Cleaning of InGaAs Surface for the Removal of Nanoparticle Contaminants for Sub-10nm Device Applications. ECS Journal of Solid State Science and Technology, 2019, 8, P3028-P3034.	1.8	17
40	Effect of Polysilicon Wettability on Polishing and Organic Defects during CMP. Journal of the Electrochemical Society, 2009, 156, H869.	2.9	16
41	Synthesis of Fe metal precipitated colloidal silica and its application to W chemical mechanical polishing (CMP) slurry. Journal of Colloid and Interface Science, 2010, 349, 402-407.	9.4	16
42	Large-Scale Plasma Patterning of Transparent Graphene Electrode on Flexible Substrates. Langmuir, 2015, 31, 2914-2921.	3.5	16
43	Development of CO ₂ gas cluster cleaning method and its characterization. Microelectronic Engineering, 2013, 102, 87-90.	2.4	15
44	Fabrication of high performance copper-resin lapping plate for sapphire: A combined 2-body and 3-body diamond abrasive wear on sapphire. Tribology International, 2018, 120, 203-209.	5.9	15
45	The Adhesion and Removal Mechanism of Ceria Particles for STI Post-CMP Cleaning Process. ECS Transactions, 2019, 92, 157-164.	0.5	15
46	Effect of Organic Acids in Copper Chemical Mechanical Planarization Slurry on Slurry Stability and Particle Contamination on Copper Surfaces. Japanese Journal of Applied Physics, 2002, 41, 1305-1310.	1.5	14
47	The Effect of Frictional and Adhesion Forces Attributed to Slurry Particles on the Surface Quality of Polished Copper. Journal of the Electrochemical Society, 2007, 154, H36.	2.9	14
48	Investigation of Source-Based Scratch Formation During Oxide Chemical Mechanical Planarization. Tribology Letters, 2013, 50, 169-175.	2.6	14
49	Mechanical deflection of a free-standing pellicle for extreme ultraviolet lithography. Microelectronic Engineering, 2015, 143, 81-85.	2.4	14
50	Nanocatalyst-induced hydroxyl radical ($\dot{\text{A}}\text{-OH}$) slurry for tungsten CMP for next-generation semiconductor processing. Journal of Materials Science, 2020, 55, 3450-3461.	3.7	14
51	Characterization of Different Cobalt Surfaces and Interactions with Benzotriazole for CMP Application. ECS Journal of Solid State Science and Technology, 2020, 9, 064005.	1.8	14
52	Fabrication of Stainless Steel Mold Using Electrochemical Fabrication Method for Microfluidic Biochip. Japanese Journal of Applied Physics, 2008, 47, 5217-5220.	1.5	13
53	Effects of size, humidity, and aging on particle removal from Si wafers. Microelectronic Engineering, 2009, 86, 145-149.	2.4	13
54	Development of inlaid electrodes for whole column electrochemical detection in HPLC. Lab on A Chip, 2009, 9, 2238.	6.0	13

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55	The Synergetic Role of Pores and Grooves of the Pad on the Scratch Formation during STI CMP. Journal of the Electrochemical Society, 2010, 157, H806.	2.9	13
56	Collapse behavior and forces of multistack nanolines. Nanotechnology, 2010, 21, 015708.	2.6	13
57	Fabrication of hydrophobic/hydrophilic switchable aluminum surface using poly(N) Tj ETQq1 1 0.784314 rgBT /Overlock 10 Tf 50 662	3.9	13
58	Study on possible root causes of contamination from an incoming PVA brush during post-CMP cleaning. Polymer Testing, 2019, 77, 105921.	4.8	13
59	Comparative evaluation of organic contamination sources from roller and pencil type PVA brushes during the Post-CMP cleaning process. Polymer Testing, 2020, 90, 106669.	4.8	13
60	Effect of Chemicals and Slurry Particles on Chemical Mechanical Polishing of Polyimide. Japanese Journal of Applied Physics, 2000, 39, 1085-1090.	1.5	12
61	Effect of Corrosion Inhibitor, Benzotriazole, in Cu Slurry on Cu Polishing. Japanese Journal of Applied Physics, 2008, 47, 108-112.	1.5	12
62	Investigation of Physical Cleaning Process Window by Atomic Force Microscope. ECS Transactions, 2009, 25, 203-210.	0.5	12
63	Effect of Acoustic Cavitation on Dissolved Gases and their Characterization during Megasonic Cleaning. ECS Transactions, 2011, 41, 101-107.	0.5	12
64	Self-assembled monolayer modified MoO ₃ /Au/MoO ₃ multilayer anodes for high performance OLEDs. Electronic Materials Letters, 2017, 13, 16-24.	2.2	12
65	Physical and Chemical Characterization of Reused Oxide Chemical Mechanical Planarization Slurry. Japanese Journal of Applied Physics, 2001, 40, 1236-1239.	1.5	11
66	Effect of Polish By-Products on Copper Chemical Mechanical Polishing Behavior. Journal of the Electrochemical Society, 2007, 154, H525.	2.9	11
67	Fundamentals of Post-CMP Cleaning. Materials Research Society Symposia Proceedings, 2007, 991, 1.	0.1	11
68	Ultrasound-induced break-in method for an incoming polyvinyl acetal (PVA) brush used during post-CMP cleaning process. Polymer Testing, 2019, 78, 105962.	4.8	11
69	Effects of Interfacial Strength and Dimension of Structures on Physical Cleaning Window. Solid State Phenomena, 0, 187, 123-126.	0.3	10
70	Investigation of oxide layer removal mechanism using reactive gases. Microelectronic Engineering, 2015, 135, 17-22.	2.4	10
71	Damage Free Particle Removal from Extreme Ultraviolet Lithography Mask Layers by High Energy Laser Shock Wave Cleaning. Japanese Journal of Applied Physics, 2008, 47, 4886-4889.	1.5	9
72	Nanoscale Particle Removal Using Wet Laser Shockwave Cleaning. ECS Journal of Solid State Science and Technology, 2012, 1, P70-P77.	1.8	9

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73	Preparation of a high hydrophobic aluminium surface by double zincating process. Journal of Adhesion Science and Technology, 2017, 31, 1061-1074.	2.6	9
74	Mechanisms of colloidal ceria contamination and cleaning during oxide post CMP cleaning. Microelectronic Engineering, 2021, 241, 111544.	2.4	9
75	Particle Removal and Its Mechanism on Hydrophobic Silicon Wafer in Highly Diluted NH ₄ OH Solutions with an Added Surfactant. Japanese Journal of Applied Physics, 2001, 40, 6182-6186.	1.5	8
76	Fluorocarbon film-assisted fabrication of a CoNi mold with high aspect ratio for nanoimprint lithography. Microelectronic Engineering, 2013, 104, 58-63.	2.4	8
77	Shockwave-induced deformation of organic particles during laser shockwave cleaning. Journal of Applied Physics, 2013, 114, 063104.	2.5	8
78	Effect of pH and chemical mechanical planarization process conditions on the copper- <i>benzotriazole</i> complex formation. Japanese Journal of Applied Physics, 2016, 55, 06JB01.	1.5	8
79	Investigation of particle agglomeration with in-situ generation of oxygen bubble during the tungsten chemical mechanical polishing (CMP) process. Microelectronic Engineering, 2019, 218, 111133.	2.4	8
80	The Hydrophilization of Process Wafers in Dilute Hydrogen Peroxide Solutions and Ozonated Deionized Water and Its Effects on Defects and Gate Oxide Integrity. Japanese Journal of Applied Physics, 1997, 36, 5416-5420.	1.5	7
81	Particle Adhesion and Removal on EUV Mask Layers During Wet Cleaning. Japanese Journal of Applied Physics, 2005, 44, 5479-5483.	1.5	7
82	Citric Acid and NaIO ₄ Based Alkaline Cleaning Solution for Particle Removal during Post-Ru CMP Cleaning. Journal of the Electrochemical Society, 2011, 158, H1052.	2.9	7
83	Hybrid Cleaning Technology for Enhanced Post-Cu/Low-Dielectric Constant Chemical Mechanical Planarization Cleaning Performance. Japanese Journal of Applied Physics, 2013, 52, 05FC02.	1.5	7
84	Quantitative Analysis of H5N1 DNA Hybridization on Nanowell Array Electrode. Journal of Nanoscience and Nanotechnology, 2013, 13, 5245-5249.	0.9	7
85	Novel one-step route to induce long-term lotus leaf-like hydrophobicity in polyester fabric. Journal of Adhesion Science and Technology, 2015, 29, 555-567.	2.6	7
86	Adsorption of sodium dodecyl sulfate on cleaning of an N-polar GaN surface in an alkaline solution. Materials Science and Engineering B: Solid-State Materials for Advanced Technology, 2017, 222, 1-6.	3.5	7
87	The Vapor Phase Deposition of Fluorocarbon Films for the Prevention of In-Use Stiction in Micromirrors. Japanese Journal of Applied Physics, 1998, 37, 7058-7063.	1.5	6
88	Point of Use Regeneration of Oxide Chemical Mechanical Planarization Slurry by Filtrations. Japanese Journal of Applied Physics, 2002, 41, 6342-6346.	1.5	6
89	Dimensionally controlled complex 3D sub-micron pattern fabrication by single step dual diffuser lithography (DDL). Microelectronic Engineering, 2015, 143, 25-30.	2.4	6
90	Effect of organic acids in dilute HF solutions on removal of metal contaminants on silicon wafer. Microelectronic Engineering, 2018, 198, 98-102.	2.4	6

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91	Effects of H ₂ O ₂ and pH on the Chemical Mechanical Planarization of Molybdenum. ECS Journal of Solid State Science and Technology, 2021, 10, 094001.	1.8	6
92	The Surface Modification with Fluorocarbon Thin Films for the Prevention of Stiction in Mems. Materials Research Society Symposia Proceedings, 1998, 518, 143.	0.1	5
93	Fabrication of Nano- and Micro-Scale UV Imprint Stamp Using Diamond-Like Carbon Coating Technology. Journal of Nanoscience and Nanotechnology, 2006, 6, 3619-3623.	0.9	5
94	Removal of Backside Particles by a Single Wafer Megasonic System. ECS Transactions, 2007, 11, 95-100.	0.5	5
95	Effect of Poly Silicon Wettability on Polymeric Residue Contamination. ECS Transactions, 2007, 11, 455-461.	0.5	5
96	Chemical and Nanomechanical Characteristics of Fluorocarbon Thin Films Deposited by Using Plasma Enhanced Chemical Vapor Deposition. Journal of the Korean Physical Society, 2007, 50, 1113.	0.7	5
97	Chemically controlled megasonic cleaning of patterned structures using solutions with dissolved gas and surfactant. Ultrasonics Sonochemistry, 2022, 82, 105859.	8.2	5
98	Effect of Corrosion Inhibitor (BTA) in Citric Acid based Slurry on Cu CMP. Materials Research Society Symposia Proceedings, 2005, 867, 131.	0.1	4
99	Damage/organic free ozonated DI water cleaning on EUVL Ru capping layer. Proceedings of SPIE, 2010, , .	0.8	4
100	Effects of pump-induced particle agglomeration during chemical mechanical planarization (CMP). , 2014, , .		4
101	Effect of Silicon Dioxide Hardness on Scratches in Interlevel Dielectric Chemical-Mechanical Polishing. Tribology Transactions, 2014, 57, 190-197.	2.0	4
102	Effect of feature spacing when injection molding parts with microstructured surfaces. Polymer Engineering and Science, 2016, 56, 1330-1338.	3.1	4
103	Adhesion and removal behavior of particulate contaminants from EUV mask materials. Colloids and Surfaces A: Physicochemical and Engineering Aspects, 2017, 535, 83-88.	4.7	4
104	Characterization of Free-Standing Nano-Membranes by Using Ellipsometry. Journal of the Korean Physical Society, 2018, 72, 868-872.	0.7	4
105	Influence of a wrinkle in terms of critical dimension variation caused by transmission nonuniformity and a particle defect on extreme ultraviolet pellicle. Journal of Micro/ Nanolithography, MEMS, and MOEMS, 2017, 16, 1.	0.9	4
106	Electrical Characterization of Slurry Particles and their Interactions with Wafer Surfaces. Materials Research Society Symposia Proceedings, 1999, 566, 173.	0.1	3
107	Frictional behavior and particle adhesion of abrasive particles during Cu CMP. Materials Research Society Symposia Proceedings, 2005, 867, 621.	0.1	3
108	The Adsorption Behaviors of Citric Acid on Abrasive Particles in Cu CMP Slurry. Materials Research Society Symposia Proceedings, 2005, 867, 751.	0.1	3

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109	The Effect of Hydrogen Peroxide on Frictional and Thermal Behaviors in a Citric Acid-Based Copper Chemical Mechanical Planarization Slurry. Japanese Journal of Applied Physics, 2008, 47, 5385.	1.5	3
110	Electrochemical Impedance Spectroscopy (EIS) Analysis of BTA Removal by TMAH during Post Cu CMP Cleaning Process. ECS Transactions, 2011, 41, 323-330.	0.5	3
111	Conductive and transparent submicron polymer lens array fabrication for electrowetting applications. Journal of Adhesion Science and Technology, 2018, 32, 1975-1986.	2.6	3
112	Study on PVA Brush Loading and Conditioning during Shallow Trench Isolation Post-CMP Cleaning Process. ECS Journal of Solid State Science and Technology, 2022, 11, 024004.	1.8	3
113	The Formation of Water Marks on Both Hydrophilic and Hydrophobic Wafers. Materials Research Society Symposia Proceedings, 1997, 477, 513.	0.1	2
114	Effect of Particle Deposition and Wet/Dry Cleaning Methods on Particle Removal Efficiency. ECS Transactions, 2007, 11, 361-367.	0.5	2
115	Fabrication of Stainless Steel Mold using Electro Chemical Fabrication (ECF) method for Microfluidic Biochip. , 2007, , .		2
116	Characteristics of High Power Laser Shock Waves and Their Cleaning Performance. ECS Transactions, 2007, 11, 41-46.	0.5	2
117	Effect of Wettability of Poly Silicon on CMP Behavior. Materials Research Society Symposia Proceedings, 2007, 991, 1.	0.1	2
118	Investigation of Surface Layer Formation for Fluorinated Carbon Film Using Fourier Transform Infrared Spectrometry Analysis. Japanese Journal of Applied Physics, 2008, 47, 6422-6426.	1.5	2
119	Particle Deposition and Adhesion. , 2008, , 167-200.		2
120	Reevaluation of Hydrogen Gas Dissolved Cleaning Solutions in Single Wafer Megasonic Cleaning. ECS Transactions, 2009, 25, 273-279.	0.5	2
121	Effective Carbon Contaminant Cleaning Condition Using Ozone Dissolved Water and Megasonic for Ru-Capped Extreme Ultraviolet Lithography Mask. Japanese Journal of Applied Physics, 2012, 51, 096503.	1.5	2
122	Effect of Alkaline pH on Polishing and Etching of Single and Polycrystalline Silicon. Japanese Journal of Applied Physics, 2012, 51, 071301.	1.5	2
123	Detection of Single Nucleotide Polymorphisms Using a Biosensor-Containing Titanium-Well Array. Journal of Nanoscience and Nanotechnology, 2013, 13, 139-143.	0.9	2
124	Removal of UV-cured resin using a hybrid cleaning process for nanoimprint lithography. Microelectronic Engineering, 2014, 114, 126-130.	2.4	2
125	Evaluation of Al CMP Slurry based on Abrasives for Next Generation Metal Line Fabrication. Korean Journal of Materials Research, 2006, 16, 731-738.	0.2	2
126	Particle Removal by Surfactants During Semiconductor Cleaning. , 2022, , 161-191.		2

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127	Determination of Optical Properties of Fluorocarbon Polymer Thin Films by a Variable Angle Spectroscopic Ellipsometry. Materials Research Society Symposia Proceedings, 1999, 588, 297.	0.1	1
128	The Adhesion of Pad Particles on Wafer Surfaces during Cu CMP. Materials Research Society Symposia Proceedings, 2005, 867, 191.	0.1	1
129	Damage Free Particle Removal from EUVL Mask Layers by High Energy Laser Shock Cleaning (LSC). , 2007, , .		1
130	Development and Optimization of Slurry for Ru CMP. Materials Research Society Symposia Proceedings, 2007, 991, 1.	0.1	1
131	Post-CMP Cleaning. , 0, , 467-509.		1
132	Effect of Laser Shock Wave Cleaning Direction on Particle Removal Behavior at Trenches. ECS Transactions, 2009, 25, 257-262.	0.5	1
133	Development of Large Area CoNi Alloy Electrodeposition Process for Stress Free Electroforming Mold. ECS Transactions, 2010, 25, 77-86.	0.5	1
134	Adhesion force change on multilayer EUVL mask due to laser induced plasma shock wave. Microelectronic Engineering, 2009, 86, 150-154.	2.4	1
135	Numerical and Experimental Evaluation of Picoliter Inkjet Head for Micropatterning of Printed Electronics. Japanese Journal of Applied Physics, 2010, 49, 05EC11.	1.5	1
136	Enhanced Fluorescence by Controlled Surface Roughness of Plastic Biochip. Japanese Journal of Applied Physics, 2011, 50, 06GL14.	1.5	1
137	Hydrophobic Modification of Diamond Conditioner for Prevention of Particle Adhesion During Oxide CMP. Journal of the Electrochemical Society, 2011, 158, H941.	2.9	1
138	Effect of Pump Pulsation on Particle Contamination on Wafer Surface in Wet Cleaning System. ECS Transactions, 2011, 41, 221-227.	0.5	1
139	Optimization of CO2 Gas Cluster Generation for Cleaning Application. ECS Transactions, 2011, 41, 237-242.	0.5	1
140	Fabrication of Large-Area CoNi Mold for Nanoimprint Lithography. Japanese Journal of Applied Physics, 2012, 51, 026503.	1.5	1
141	Role of mask patterns in fabrication of Si nanotip arrays. Micro and Nano Letters, 2013, 8, 27-31.	1.3	1
142	Removal of Nano-sized Particles Using Carbon Dioxide (CO2) Gas Cluster Cleaning without Pattern Damage. Particulate Science and Technology, 2015, 33, 558-561.	2.1	1
143	Multistack structure for an extreme-ultraviolet pellicle with out-of-band radiation reduction. Journal of Micro/ Nanolithography, MEMS, and MOEMS, 2015, 14, 043501.	0.9	1
144	Impact of non-uniform wrinkles for a multi-stack pellicle in EUV lithography. , 2017, , .		1

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145	Contamination Removal From UV and EUV Photomasks. , 2017, , 135-173.		1
146	Area-Selective Atomic Layer Deposition Using Inkjet-Printed Fluorocarbon Patterns as Mask Layers. Digest of Technical Papers SID International Symposium, 2018, 49, 1478-1481.	0.3	1
147	Metal Surface Chemical Composition and Morphology. , 2018, , 579-618.		1
148	Fabrication and Characterization of the 32 x 32 Array Digital Si-PIN X-ray Detector for Single Photon Counting Image Sensor. Journal of the Korean Physical Society, 2010, 57, 44-50.	0.7	1
149	Optimization of FPD Cleaning System and Processing by Using a Two-Phase Flow Nozzle. Korean Journal of Materials Research, 2014, 24, 429-433.	0.2	1
150	The Vapor Phase Deposition Of Fluorocarbon Films For The Prevention Of In-Use Stiction In Micromirrors. , 1998, , .		0
151	Laser shock removal of nanoparticles from Si capping layer of EUV mask. , 2004, , .		0
152	Effects of Additives in KOH Based Electrolytes on Cu ECMP. Materials Research Society Symposia Proceedings, 2007, 991, 1.	0.1	0
153	SAM Modification of CMP Conditioner for the Prevention of Particle Adhesion. ECS Transactions, 2009, 25, 95-99.	0.5	0
154	Effect of Rinse Process on Removal of Crown Type Defects during Photoresist Development. Japanese Journal of Applied Physics, 2011, 50, 016505.	1.5	0
155	Nano Gas Cluster Dry Cleaning for Damage Free Particle Removal. ECS Transactions, 2011, 41, 229-236.	0.5	0
156	Optimization of DIO3 with Megasonic Cleaning of Ru Capped EUVL Mask for Effective Carbon Contaminant Removal. ECS Transactions, 2011, 41, 131-138.	0.5	0
157	CMP Defects; Their Detection and Analysis on Root Causes. ECS Transactions, 2012, 44, 559-564.	0.5	0
158	The effect of fluid pH for 2-body lapping process. , 2014, , .		0
159	Investigation of Cu-BTA complex formation and removal on various Cu surface conditions. , 2014, , .		0
160	Multi-stack extreme-ultraviolet pellicle with out-of-band reduction. , 2015, , .		0
161	Patterning dependence on the mask defect for extreme ultraviolet lithography. , 2015, , .		0
162	Impact of the non-uniform intensity distribution caused by a meshed pellicle of extreme ultraviolet lithography. Microelectronic Engineering, 2015, 143, 31-36.	2.4	0

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163	Influence of non-uniform intensity distribution of deformed pellicle for N7 patterning. Proceedings of SPIE, 2016, , .	0.8	0
164	Critical dimension variation caused by wrinkle in extreme ultra-violet pellicle for 3-nm node. Japanese Journal of Applied Physics, 2017, 56, 106501.	1.5	0
165	Removal of EUV exposed hydrocarbon from Ru capping layer of EUV mask using the mixture of alkaline solutions and organic solvents. Colloids and Surfaces A: Physicochemical and Engineering Aspects, 2018, 555, 72-79.	4.7	0
166	Selection of CVD Diamond Crystal Size on a CVD Pad Conditioner for Improved Lifetime. Electronic Materials Letters, 2019, 15, 357-362.	2.2	0
167	Fabrication of Stainless Steel Metal Mask with Electrochemical Fabrication Method and Its Improvement in Dimensional Uniformity. Electronic Materials Letters, 2019, 15, 7-17.	2.2	0
168	Hybrid DHF and N2 jet spray cleaning for silicon nitride and metal layer DRAM patterns. Microelectronic Engineering, 2020, 220, 111171.	2.4	0
169	Latest developments in the understanding of PVA brush related issues during post CMP (pCMP) cleaning. , 2022, , 591-627.		0
170	The Deposition and Characterization of 10 nm Thick Teflon-like Anti-stiction Films for the Hot Embossing. Korean Journal of Materials Research, 2005, 15, 149-154.	0.2	0
171	Optimizing the Plasma Deposition Process Parameters of Antistiction Layers Using a DOE (Design of Tj ETQq1 1 0.784314 rgBT /Over 0.2	0.2	0
172	Fabrication of PMMA Micro CE Chip Using IPA Assisted Low-temperature Bonding. Korean Journal of Materials Research, 2006, 16, 99-105.	0.2	0
173	Fabrication and Characterization of an Antistiction Layer by PECVD (plasma enhanced chemical vapor) Tj ETQq1 1 0.784314 rgBT /Over 0.2	0.2	0
174	Dishing and Erosion Evaluations of Tungsten CMP Slurry in the Orbital Polishing System. Transactions on Electrical and Electronic Materials, 2006, 7, 163-166.	1.9	0
175	Deposition and Characterization of Antistiction Layer for Nanoimprint Lithography by VSAM (Vapor) Tj ETQq1 1 0.784314 rgBT /Over 0.2	0.2	0
176	Multiple Duplication of Electroformed Nano-Ni Stamps from Si Mother Mold. , 2008, , .		0
177	The Effect of Electrolytes on Polishing Behavior in Cu ECMP. Korean Journal of Materials Research, 2008, 18, 334-338.	0.2	0
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